

(0.80 mm) .0315"

ERF8 SERIES

RUGGED HIGH-SPEED SOCKET

SPECIFICATIONS

Insulator Material: Black LCP
Contact Material: Plating: Au or Sn over 50 μ" (1.27 μm) Ni Current Rating: 2.2 A per pin (2 pins powered) Operating Temp Range:
-55 °C to + 125 °C
Voltage Rating:
225 VAC / 318 VDC
ROHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity: (0.10 mm) .004" max (005-030) (0.12 mm) .005" max (040-060) (0.15 mm) .006" max (070-100)* (.004" stencil solution may be available)

RECOGNITIONS



Yes

ALSO AVAILABLE (MOQ Required)

APPLICATIONS

POS. PART NOs.

10 ASP-148421-01 ERF8-DV

11 ASP-137969-01 ERF8-DV

25 ASP-148422-01 ERF8-DV

35 ASP-135029-01 ERF8-DV

40 ASP-148424-01 ERF8-DV

ASP-130367-01 ERF8-DV

ASP-137973-01

23 ASP-130368-01

· Mezzanine stack heights

STANDARD

NEXUS5001™.org

NEXUS5001™.org

POWER.org

ARM/HSSTP

POWER.org¹

Notes:

Patented

non-returnable.

Some lengths, styles and options are non-standard,

Board Mates:

Cable Mates:

ERF8

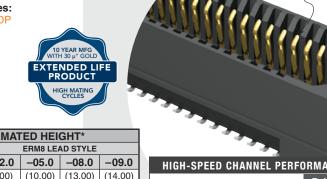
SERIES

ERF8-DV

ERF8-DV

(3.35)

ERCD, ERDF



Robust Edge Rate® contact improves

"Zippered"

unmating

FRF8 LEAD STYLE -02.0(13.00) (14.00) (7.00) .276 (10.00)-05.0 .551 (9.00)(12.00)(15.00) (16.00) -07.0 .354 .472 .591 .629 (17.00)(11.00)(14.00)(18.00)-09.0 .453 .551 .669 .709

*Processing conditions will affect mated height.

HIGH-SPEED CHANNEL PERFORMANCE

ERM8/ERF8 @ 7 mm Mated Stack Height

Rating based on Samtec reference channel.

PAM4

10 to 200 I/Os

POWER/SIGNAL **APPLICATION** mmm

(1.50 mm)

.059" NOMINAL

WIPE

Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

NO. OF POSITIONS PER ROW

No. of Positions x

-L & -EGP = No. of Positions x- (0.80) .0315 + (7.50) .295

-EGPS = No. of Positions x

(0.80) .0315 + (10.00) .394

(0.80) .0315 + (6.00) .236

LEAD **STYLE** **PLATING OPTION**

DV

OTHER OPTION

·TR

=Tape &

Reel

Packaging

(Not

available

with 100

positions)

-005, -010, -011,–013**.** –020. –025. -030, -035 -040, -049 050, -060, -070, -075

-100 (Available with -05.0 lead style only) Specify **LEAD** STYLE from chart

LEAD Α (5.10) .200 05.0 (7.00)-07.0 .276 (9.00)-09.0

(5.60)

.220

01

= 10 μ" (0.25 µm) Gold on contact, **Matte Tin** on tail

–S = 30 µ" (0.76 µm) Gold on contact, Matte Tin on tail

(7.25)

.285

= Latching (Lead Style -05.0 only) (Not available with <u>-EGP or -EGPS</u> options)

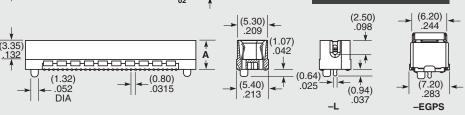
-EGP

= Extended Guide Post (Lead Style -07.0 only) (Not available with -L & -EGPS option)

-EGPS

Extended Guide Post Shield (Lead Style -07.0 only) (Not available with _ & -EGP option) (-010, -020, -025, -030 only)

= (6.00 mm) .236" DIA Polyimide Film Pick & Place Pad



מר

-EGP

Due to technical progress, all designs, specifications and components are subject to change without notice WWW.TOBY.CO.UK











(0.80 mm) .0315"

ERF8-RA, ERF8-EM SERIES

RUGGED EDGE RATE® STRIPS

ERF8-RA / ERF8-EM Board Mates:

ERF8-RA Cable Mates:

ERCD, ERDP

SPECIFICATIONS

Insulator Material:
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Contact Material:
BeCu
Plating:
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Current Rating:
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(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
Voltage Rating:
225 VAC / 318 VDC
RoHS Compliant:

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity (ERF8-RA): (0.10 mm) .004" max SMT Lead Coplanarity (ERF8-EM): (0.10 mm) .004" max (005-030)

(0.10 mm) .004" max (005-030) (0.12 mm) .005" max (040-075)* *(.004" stencil solution may be available)

RECOGNITIONS

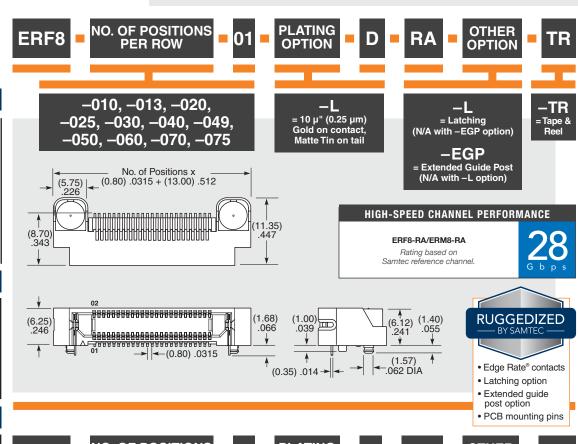


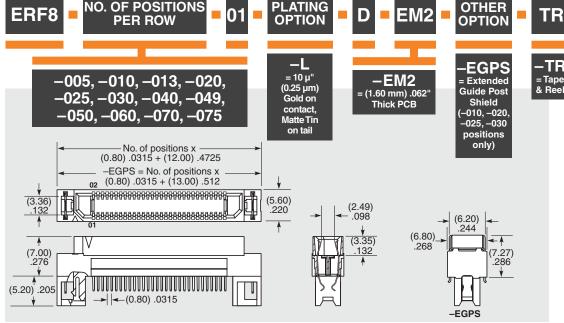
ALSO AVAILABLE (MOQ Required)

- Other Positions
- Solder leads & weld tab for (2.36 mm) .093" thick board
- Solder leads & weld tab for (2.36 mm) .093" thick PCB (ERF8-RA only
- Other platings

Notes: Patented

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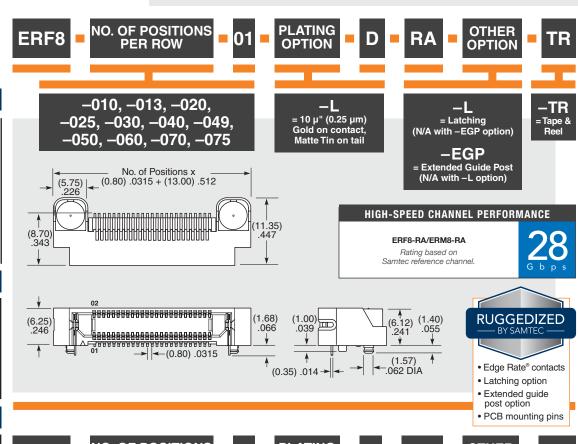


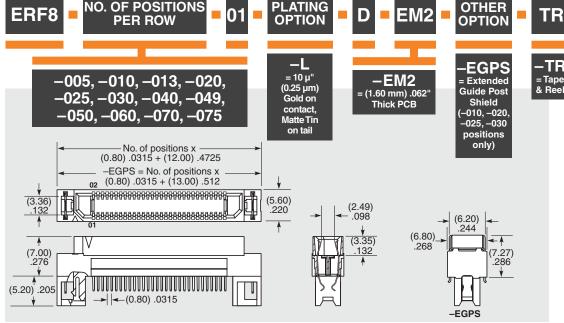
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